

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Foong Wei KUONG</td> <td>03/20/2013</td> </tr> <tr> <td>Goh Kok SING</td> <td>03/20/2013</td> </tr> <tr> <td>Shamal MUNDIYATH</td> <td>03/20/2013</td> </tr> </tbody> </table>		Name	Execution Date	Foong Wei KUONG	03/20/2013	Goh Kok SING	03/20/2013	Shamal MUNDIYATH	03/20/2013
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Foong Wei KUONG	03/20/2013								
Goh Kok SING	03/20/2013								
Shamal MUNDIYATH	03/20/2013								
RECEIVING PARTY DATA									
Name:	JF Microtechnology Sdn. Bhd.								
Street Address:	Lot 6, Jalan Teknologi 3/6								
Internal Address:	Taman Sains Selangor 1, Kota Damansara								
City:	Petaling Jaya, Selangor								
State/Country:	MALAYSIA								
Postal Code:	47810								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13848209</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13848209				
Property Type	Number								
Application Number:	13848209								
CORRESPONDENCE DATA									
Fax Number:	4352521361								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone:	4352521360								
Email:	tkellogg@mabr.com								
Correspondent Name:	R. Burns Israelsen								
Address Line 1:	1389 Center Drive, Suite 300								
Address Line 4:	Park City, UTAH 84098								
ATTORNEY DOCKET NUMBER:	P1718.10001US01								
NAME OF SUBMITTER:	R. Burns Israelsen								
This document serves as an Oath/Declaration (37 CFR 1.63).									
Total Attachments: 3									
source=P1718-10001US01-Declaration_Assignment#page1.tif									
source=P1718-10001US01-Declaration_Assignment#page2.tif									
source=P1718-10001US01-Declaration_Assignment#page3.tif									

OP \$40.00 13848209

Title of Invention	GROUND CONTACT OF AN INTEGRATED CIRCUIT TESTING APPARATUS
Docket Number	PU718.108011/US01

As the below named inventor, I hereby declare that:
 This declaration is directed to: The attached application, or United States application or PCT international application number filed on _____

The above-identified application was made or authorized to be made by me.
 I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.
 I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

WHEREAS, JF Microtechnology Sdn. Bhd. (hereinafter referred to as "ASSIGNEE") having a place of business at: Lot 5, Jalan Teknologi 1/6, Taman Sains Selangor 1, Kota Damansara, 47810 Petaling Jaya, Selangor, Malaysia, desires to acquire the entire right, title and interest in said invention and the above-identified United States patent application.

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I hereby assign to the ASSIGNEE, the entire right, title and interest in said invention and in the above-identified United States patent application and in all divisions, continuations and continuations-in-part of said application, and reissues, extensions and renewals of Letters Patent granted thereon, and in all corresponding patent applications filed in countries foreign to the United States ("foreign countries") and corresponding international patent applications, and in all Letters Patents issuing on any such patent applications in the United States and foreign countries.

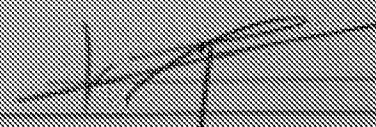
I hereby assign to the ASSIGNEE the right to file patent applications in foreign countries on said invention in its own name and the right to claim priority to the above-identified United States patent application under the terms of the International Convention and any other relevant treaties;

I hereby authorize and request the United States Patent & Trademark Office and officials in patent offices in foreign countries to issue any and all of said Letters Patent to the ASSIGNEE, as the assignee of my entire right, title and interest in and to the same, for the sole use and behoof of the ASSIGNEE, its successors, assigns, and legal representatives, to the full end of the term for which said Letters Patent may be granted; and

Further, I agree that, without further consideration, I will communicate to the ASSIGNEE any facts known to me respecting said invention, and testify in any legal proceeding; sign all lawful papers, execute all divisional, continuation, continuation-in-part, substitute, renewal and reissue applications, execute all necessary assignment papers to cause said Letters Patent to be issued to the ASSIGNEE, make all rightful oaths, and, perform all lawful acts to aid the ASSIGNEE, its successors and assigns, to obtain and enforce Letters Patent for said invention in the United States and foreign countries.

LEGAL NAME OF INVENTOR

Inventor: Foong Wei Kuong Date: 20th March 2013

Signature: 

MASCHOFF BRENNAN, PLLC
 1389 Center Drive, SUITE 300
 PARK CITY, UTAH 84098, USA

DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

Title of Invention GROUND CONTACT OF AN INTEGRATED CIRCUIT TESTING APPARATUS

Docket Number P1718.10001US01

As the below named inventor, I hereby declare that:
This declaration is directed to: The attached application, or United States application or PCT international application number _____ filed on _____

The above-identified application was made or authorized to be made by me.
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.
I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

WHEREAS, JF Microtechnology Sdn. Bhd. (hereinafter referred to as "ASSIGNEE") having a place of business at: Lot 6, Jalan Teknologi 3/6, Taman Sains Selangor 1, Kota Damansara, 47810 Petaling Jaya, Selangor, Malaysia, desires to acquire the entire right, title and interest in said invention and the above-identified United States patent application;

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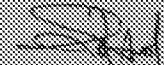
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Further, I agree that, without further consideration, I will communicate to the ASSIGNEE any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, continuation-in-part, substitute, renewal and reissue applications, execute all necessary assignment papers to cause said Letters Patent to be issued to the ASSIGNEE, make all rightful oaths, and, perform all lawful acts to aid the ASSIGNEE, its successors and assigns, to obtain and enforce Letters Patent for said invention in the United States and foreign countries.

LEGAL NAME OF INVENTOR

Inventor: Shamal Mundiayath Date: 20/03/13

Signature: 

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1389 Center Drive, SUITE 300
PARK CITY, UTAH 84098, USA

PATENT